1 Package summary

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<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
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<td>8</td>
<td>-</td>
<td>mm</td>
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<tr>
<td>package width</td>
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<td>-</td>
<td>mm</td>
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<td>mm</td>
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<td>nominal pitch</td>
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<td>0.5</td>
<td>-</td>
<td>mm</td>
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<tr>
<td>actual quantity of termination</td>
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<td>56</td>
<td>-</td>
<td></td>
</tr>
</tbody>
</table>

Table 1. Package summary

Terminal position code: Q (quad)
Package type descriptive code: HVQFN56
Package style descriptive code: HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type: P (plastic)
Mounting method type: S (surface mount)
Issue date: 30-10-2018
Manufacturer package code: 98ASA01086D
2 Package outline

Figure 1. Package outline HVQFN56 (SOT684-21(DD/SC))
Figure 2. Package outline detail HVQFN56 (SOT684-21(DD/SC))
Figure 3. Package outline bottom view HVQFN56 (SOT684-21(DD/SC))
3 Soldering

Figure 4. Reflow soldering footprint part1 for HVQFN56 (SOT684-21(DD/SC))
Figure 5. Reflow soldering footprint part2 for HVQFN56 (SOT684-21(DD/SC))
Figure 6. Reflow soldering footprint part3 for HVQFN56 (SOT684-21(DD/SC))
NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
3. PIN ONE CONFIGURATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON–FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.25 MM.
6. ANCHORING PADS.

Figure 7. Package outline note HVQFN56 (SOT684-21(DD/SC))
4 Legal information

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